# SY21314

## High Efficiency 33V, 1MHz, 4A Current Limit Step-Up Regulator

## General Description

The SY21314 high efficiency step-up regulator operates using current mode control over a wide input voltage range from 3V to 33V. It integrates an N-channel MOSFET with low 120mΩ $R_{DS(ON)}$ to minimize conduction loss.

The 1MHz switching frequency and internal compensation reduce external inductor and capacitor sizes, and the built-in internal soft-start circuitry minimizes inrush current at startup.

The device offers overcurrent and thermal shutdown protections.

The SY21314 is available in a compact DFN3x3-10 package.

## Features

- 3V to 33V Input Voltage Range
- 33V Maximum Output Voltage
- 4A Main MOSFET Current Limit
- 15 μA Shutdown Current (Max.)
- 100 μA Quiescent Current (Typ.)
- Low $R_{DS(ON)}$ for Internal N-Channel MOSFET: 120mΩ
- 1MHz Switching Frequency
- Internal Soft-Start
- ±2% 0.6V Reference
- Cycle-by-Cycle Peak Current Limit
- Overtemperature Protection
- RoHS-Compliant and Halogen-Free
- Compact DFN3mmx3mm-10 Package

## Applications

- Portable Devices
- Battery Powered Systems
- Networking Cards Powered from PCI or PCI-Express Slots

## Typical Application

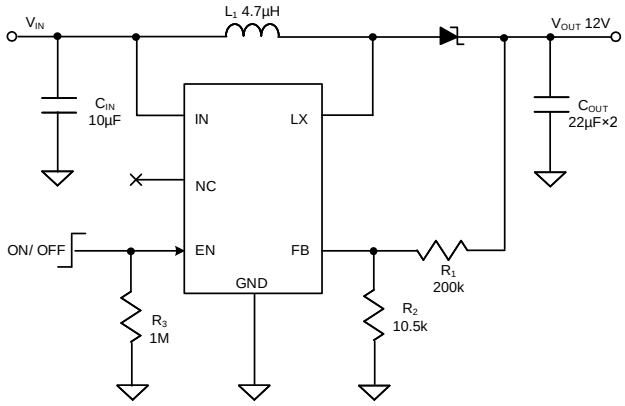



*Figure 1. Typical Application Circuit*

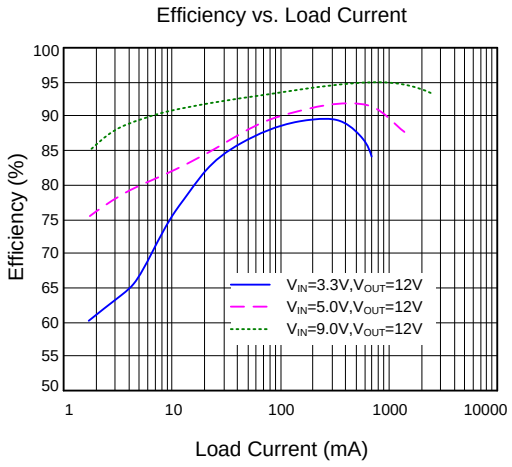


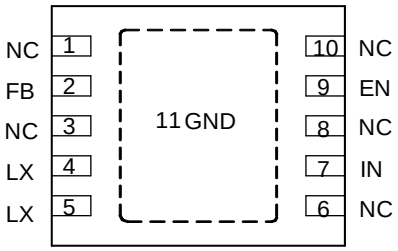

*Figure 2. Efficiency vs. Output Current*

## Ordering Information

| Ordering Part Number | Package Type | Top Mark |
|---|---|---|
| SY21314DBC | DFN3×3-10<br>RoHS-Compliant and Halogen-Free | ***VIxyz*** |

***x = year code, y = week code, z = lot number code***

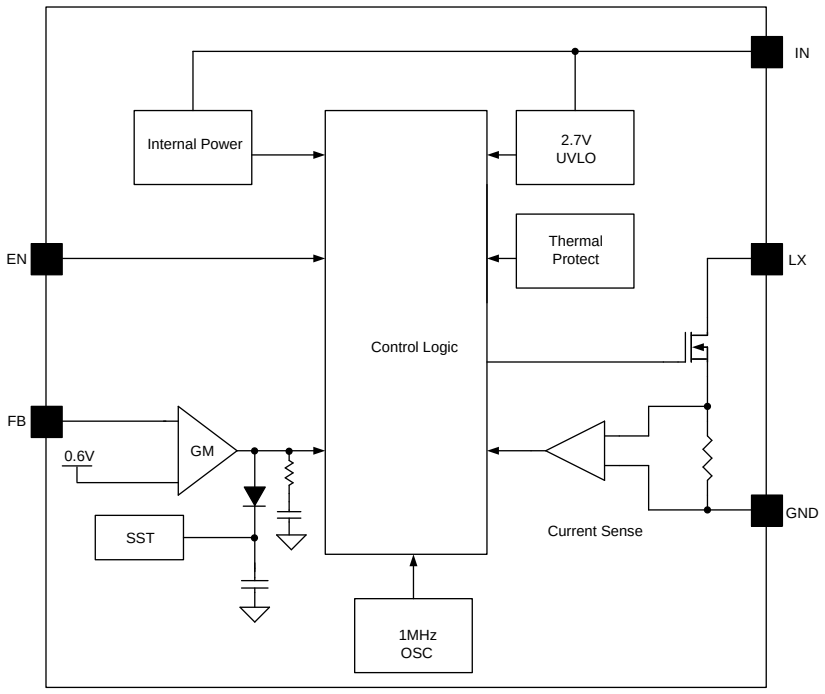
## Pinout (top view)




## Pin Description

| Pin Number | Pin Name | Pin Description |
|---|---|---|
| 1,3,6,8,10 | NC | No connection. |
| 2 | FB | Feedback pin. Connect a resistor R1 between $V_{OUT}$ and FB, and a resistor R2 between FB and GND to program the output voltage: $V_{OUT}$ = 0.6V × (R1/R2+1). |
| 4,5 | LX | Inductor node. Connect an inductor between the IN and LX pins. |
| 7 | IN | Input pin. Decouple this pin to the GND pin with a 1μF ceramic capacitor. |
| 9 | EN | Enable pin. Drive low to disable the device, drive high to enable. Do not leave floating. |
| 11 | GND | Ground pin. Connect to system GND. |

## Block Diagram



## Absolute Maximum Ratings

| Parameter (Note1) | Min | Max | Unit |
|---|---|---|---|
| LX, IN, EN | -0.3 | 36 | V |
| FB | -0.3 | 4 | |
| LX, 50ns Duration | IN+3 | GND-4 | |
| Lead Temperature (Soldering, 10 sec.) | | 260 | °C |
| Junction Temperature, Operating | -40 | 150 | |
| Storage Temperature | -65 | 150 | |

## Thermal Information

| Parameter (Note2) | Typ | Unit |
|---|---|---|
| $\theta_{JA}$ Junction-to-ambient Thermal Resistance | 38 | °C/W |
| $\theta_{JC}$ Junction-to-case Thermal Resistance | 8 | |
| $P_D$ Power Dissipation $T_A$=25°C | 2.6 | W |

## Recommended Operating Conditions

| Parameter (Note3) | Min | Max | Unit |
|---|---|---|---|
| IN | 3 | 33 | V |
| Junction Temperature, Operating | -40 | 125 | °C |
| Ambient Temperature | -40 | 85 | |

## Electrical Characteristics

($V_{IN}$ = 5V, $V_{OUT}$=12V, $I_{OUT}$=100mA, $T_A$ = 25°C unless otherwise specified)

| Parameter | Symbol | Test Conditions | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| Input Voltage Range | $V_{IN}$ | | 3 | | 33 | V |
| Quiescent Current | $I_Q$ | $V_{FB}$ = 0.66V | | 100 | | μA |
| Shutdown Current | $I_{SHDN}$ | EN = 0 | | | 15 | μA |
| Low Side Main FET $R_{ON}$ | $R_{DS(ON)}$ | | | 120 | | mΩ |
| Main FET Current Limit | $I_{LIM}$ | Duty cycle = 80% | 4 | | 6 | A |
| Switching Frequency | fsw | | 0.8 | 1 | 1.2 | MHz |
| Feedback Reference Voltage | $V_{REF}$ | | 0.588 | 0.6 | 0.612 | V |
| FB Pin Input Current | $I_{FB}$ | | -50 | | 50 | nA |
| IN UVLO Rising Threshold | $V_{IN,UVLO}$ | | | | 2.7 | V |
| UVLO Hysteresis | $U_{VLO,HYS}$ | | | 0.1 | | V |
| EN Rising Threshold | $V_{ENH}$ | | 2 | | | V |
| EN Falling Threshold | $V_{ENL}$ | | | | 0.4 | V |
| Maximum Duty Cycle | $D_{MAX}$ | | | 90 | | % |
| Thermal Shutdown Temperature | $T_{SD}$ | | | 150 | | °C |
| Thermal Recovery Hysteresis | $T_{HYS}$ | | | 15 | | °C |

**Note 1**: Stresses beyond the “Absolute Maximum Ratings” may cause permanent damage to the device. These are stress ratings only. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

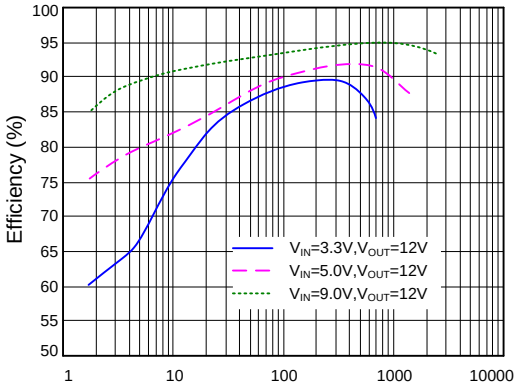
**Note 2**: $\theta_{JA}$ is measured in the natural convection at $T_A$ = 25°C on a low effective single layer thermal conductivity test board of JEDEC 51-3 thermal measurement standard. Test condition: Device mounted on 2” x 2” FR-4 substrate PCB, 2oz copper, with minimum recommended pad on top layer and thermal vias to bottom layer ground plane.

**Note 3:** The device is not guaranteed to function outside its operating conditions.

# Typical Performance Characteristics

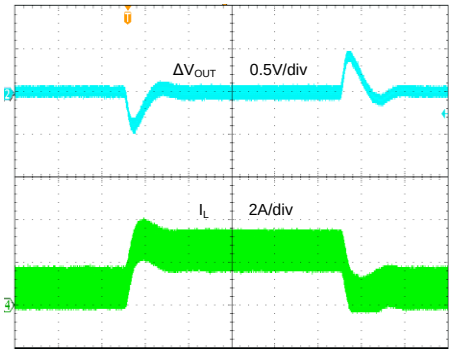
($T_A$= 25℃, $V_{IN}$=5V, $V_{OUT}$ = 12V, L = 2.2μH, $C_{OUT}$= 44μF, unless otherwise specified.)

Efficiency vs. Load Current



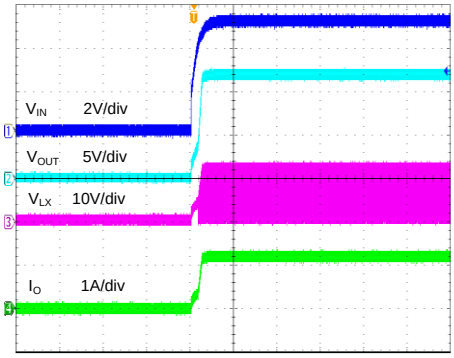

Load Transient

($V_{IN}$=5.0V, $V_{OUT}$=12V, $I_O$=0.12 ~ 1.2A)



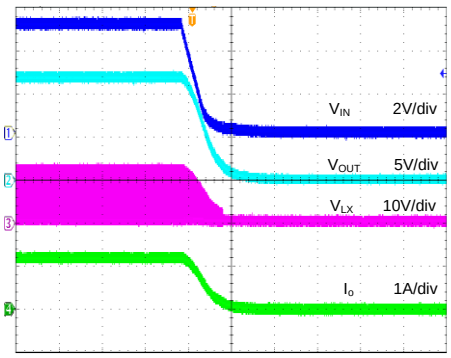

Startup from $V_{IN}$

($V_{IN}$=5.0V, $V_{OUT}$=12V, $I_O$=1.2A)



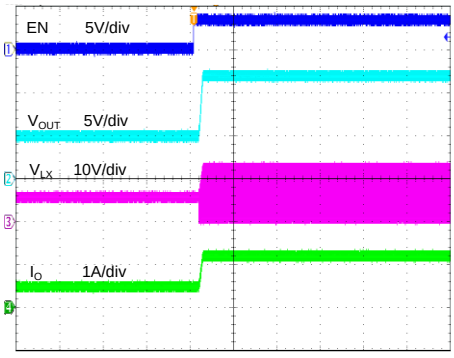

Shutdown from $V_{IN}$

($V_{IN}$=5.0V, $V_{OUT}$=12V, $I_O$=1.2A)



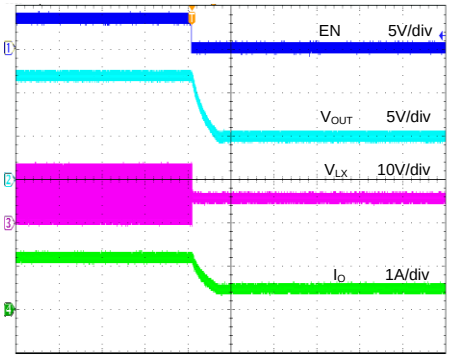

Startup from Enable

($V_{IN}$=5.0V, $V_{OUT}$=12V, $I_O$=1.2A)



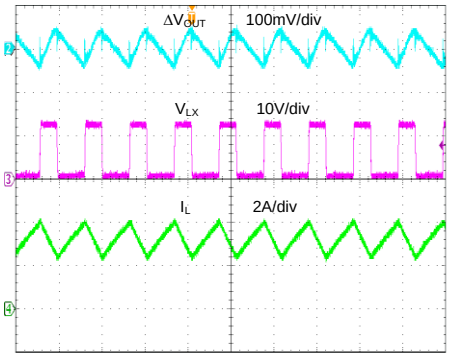

Shutdown from Enable

($V_{IN}$=5.0V, $V_{OUT}$=12V, $I_O$=1.2A)



Output Ripple

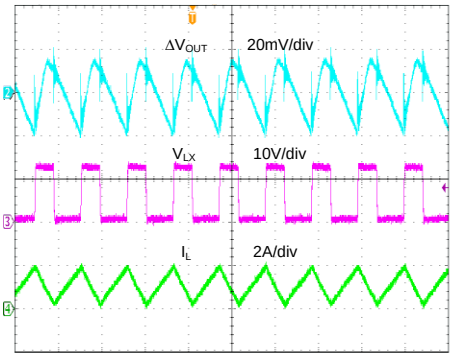
($V_{IN}$=5.0V, $V_{OUT}$=12V, $I_O$=1.2A)




Time (1μs/div)

Output Ripple

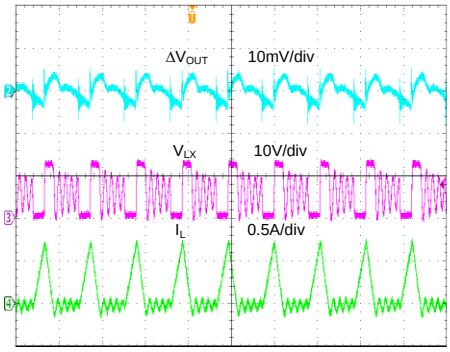
($V_{IN}$=5.0V, $V_{OUT}$=12V, $I_O$=0.6A)




Time (1μs/div)

Output Ripple

($V_{IN}$=5.0V, $V_{OUT}$=12V, $I_O$=0.06A)




Time (1μs/div)

## Detailed Description

The SY21314 high efficiency step-up regulator operates using current mode control, over a wide input voltage range from 3V to 33V. It integrates an N-channel MOSFET with low 120mΩ $R_{DS(ON)}$ to minimize conduction loss.

The 1MHz switching frequency and internal compensation reduce external inductor and capacitor sizes, and the built-in internal soft-start circuitry minimizes inrush current at startup.

### Enable Operation

Driving the EN pin high (>2V) enables normal operation. Driving the EN pin low (<0.4V) places the device in shutdown mode. During shutdown mode, the SY21314 current drops to less than 15μA.

### Soft-Start (EN Control)

The SY21314 has a built-in soft-start to control the rising slew rate of the output voltage and limit the input current surge during IC startup. With a 200μs turn-on delay time before the initial soft-start, the typical soft-start time is 1ms.

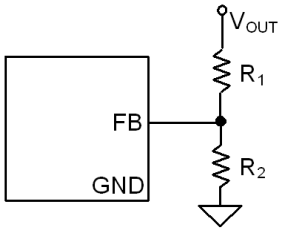
## Application Information

The following paragraphs describe the selection process for the feedback resistors (R1 and R2), input capacitor $C_{IN}$, output capacitor $C_{OUT}$, boost inductor L, and diode D.

### Feedback Resistor-Divider R1 and R2

Choose R1 and R2 to program the proper output voltage. Choose large resistance values between 10kΩ and 1MΩ for both R1 and R2 to minimize power consumption under light loads. If a value of 200kΩ is chosen for R1, then R2 can be calculated as:

$$R2 = \frac{0.6V}{V_{OUT}\text{-}0.6V} R1$$




### Input Capacitor $C_{IN}$

Input filter capacitors reduce the ripple voltage on the input, filter the switched current drawn from the input supply, and reduce the EMI. When selecting an input capacitor, be sure to select a voltage rating at least 20% greater than the maximum voltage of the input supply and a temperature rating higher than the system requirements. X5R series ceramic capacitors are most often selected due to their small size, low cost, surge-current capability, and high RMS current ratings over a wide temperature and voltage range. However, systems that are powered by a wall adapter or other long and therefore inductive cabling may be susceptible to significant inductive ringing at the input to the device. In these cases, consider adding some bulk capacitance like electrolytic, tantalum, or polymer type capacitors. Using a combination of bulk capacitors (to reduce overshoot or ringing) in parallel with ceramic capacitors (to meet the RMS current requirements) is helpful in these cases.

Consider the RMS current rating of the input capacitor, paralleling additional capacitors if required to meet the calculated RMS ripple current.

$$I_{CIN\_RMS} = \frac{V_{IN} \cdot (V_{OUT} - V_{IN})}{2\sqrt{3} \cdot L \cdot F_{SW} \cdot V_{OUT}}$$

For the best performance, select a typical X5R or better grade low ESR 10μF ceramic capacitor and place it as close as possible to the IN and GND pins. Take care to minimize the loop area formed by $C_{IN}$ and the IN/GND pins.

### Output Capacitor $C_{OUT}$

Select the output capacitor $C_{OUT}$ to handle the output ripple requirements. Both steady state ripple and transient requirements must be taken into consideration when selecting the component. For the best performance, use an X5R or better grade ceramic capacitor with capacitance of at least 22μF.

For applications where the design must meet stringent ripple requirements, the following considerations must be followed:

The output voltage ripple at the switching frequency is caused by the inductor current ripple ($\Delta I_L$) on the output capacitor's ESR (ESR ripple), as well as the stored charge (capacitive ripple). When calculating total ripple, both should be considered.

$$V_{RIPPLE,\ ESR1} = I_{LPEAK} \times ESR$$

$$V_{RIPPLE,\ ESR2} = I_{LVALLEY} \times ESR$$

$$V_{RIPPLE,CAP} = \frac{I_{OUT} \times (1\text{-}D)}{C_{OUT} \times f_{SW}}$$

The measured capacitive ripple might be higher than the calculated value because the effective capacitance for ceramic capacitors decreases with the voltage across the terminals. The voltage derating is usually included as a chart in the capacitor datasheet, and the ripple can be recalculated after taking the target output voltage into account.

**Boost Inductor L**

Consider the following when choosing this inductor:

1) Choose the inductance to provide a ripple current that is approximately 40% of the maximum output current. The recommended inductance is calculated as:

$$L = \left(\frac{V_{IN}}{V_{OUT}}\right)^2 \frac{V_{OUT} - V_{IN}}{f_{SW}\, I_{OUT,MAX} \times 0.4}$$

where $f_{SW}$ is the switching frequency and $I_{OUT,MAX}$ is the maximum load current.

The SY21314 has high tolerance for ripple current amplitude variation. As a result, the final choice of inductance can vary slightly from the calculated value with no significant performance impact.

2) The inductor's saturation current rating must be greater than the peak inductor current under full load:

$$I_{SAT,MIN} = \left(\frac{V_{OUT}}{V_{IN}}\right) \times I_{OUT,MAX} + \frac{V_{IN}(V_{OUT} - V_{IN})}{2 \times f_{SW} \times L \times V_{OUT}}$$

3) The DCR of the inductor and the core loss at the switching frequency must be low enough to achieve the desired efficiency requirement. Choose an inductor with DCR less than 10mΩ to achieve good overall efficiency.

**Rectifier Diode**

For high efficiency, choose a Schottky diode with low forward voltage drop and fast reverse recovery. The maximum current rating of the diode must be higher than the maximum input current, and the average current rating of the diode must be higher than the output current. The reverse breakdown voltage must be higher than the maximum output voltage.

**Maximum Output Current Estimation**

The maximum current that the converter can provide to the load depends on the output voltage / input voltage ratio.

Use the following formulas to evaluate an approximate max current that the converter can deliver when driving the load.

$$D = 1 - V_{IN(MIN)} \times \frac{\eta}{V_{OUT}}$$

Estimate the maximum output current:

$$I_{MAXOUT} = (IL_{MIN} - \frac{\Delta IL}{2}) \times \frac{\eta \times V_{IN(MIN)}}{V_{OUT}}$$

$$I_{MAXOUT} = \left(I_{LIM(MIN)} - \frac{\Delta IL}{2}\right) \times (1-D)$$

Where: $V_{IN(MIN)}$ is the minimum voltage at the boost input in the application, $IL_{MIN}$ is the minimum device current datasheet limit (4A for SY21314), $\Delta IL$ is the current ripple and η is the efficiency, which can be substituted with a value of 0.8 for simplicity.

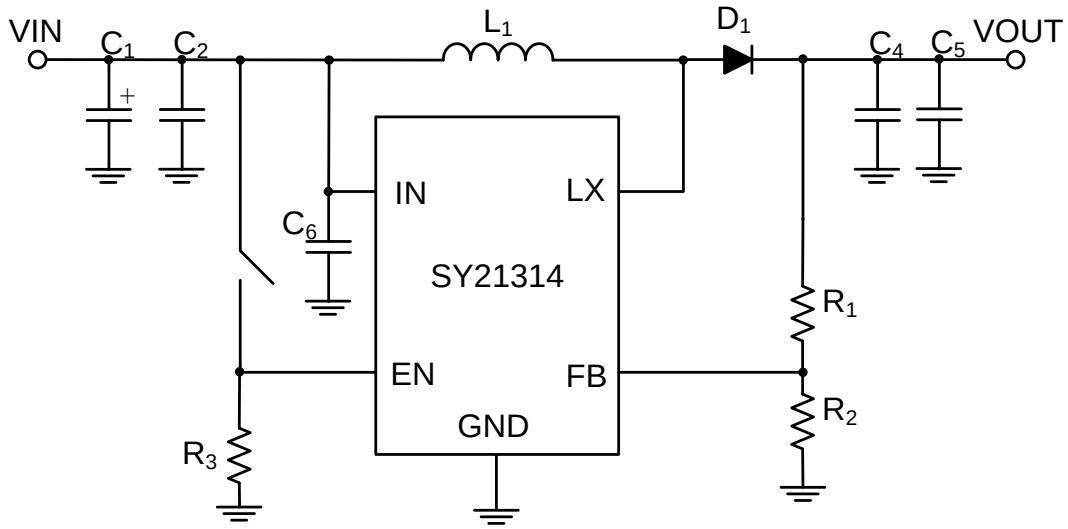
**Thermal Protection**

The SY21314 includes over temperature protection circuitry to prevent overheating due to excessive power dissipation. This will shut down the device when the junction temperature exceeds 150°C. When the junction temperature cools down by approximately 15°C, the device will resume normal operation after a complete soft-start cycle. For continuous operation, provide adequate cooling so that the junction temperature does not exceed the thermal protection threshold.

**Over Current Protection**

The SY21314 provides a cycle-by-cycle overcurrent protection and turns off the main power MOSFET once the inductor current reaches the overcurrent limit threshold. During the overcurrent protection, the output voltage drops as a function of the load. If the output voltage drops below the input voltage, the current will directly flow through L and rectifier diode. In this case the current is only limited by the DC resistance in the path during the event. As soon as the overload condition is removed, the converter resumes operation.

## Application Schematic




## Design Specifications

| Input Voltage (V) | Output Voltage(V) | Output Current Limit (A) |
|---|---|---|
| 3–12 | 12 | 1.2 |

## BOM List

| Reference Designator | Description | Part Number | Manufacturer |
|---|---|---|---|
| U1 | 4A, 1MHz Sync Boost(DFN3X3-10) | SY21314DBC | Silergy |
| L1 | 2.2μH/6A inductor | VLP6045LT-2R2N | TDK |
| C1 | 47μF/50V(electrolytic capacitor) | | |
| C2, C4, C5 | 22μF/25V,1206,X5R | C3216X5R1E226M | TDK |
| C6 | 0.1μF/25V, 0603, X5R | GRM188R61E104K | muRata |
| D1 | 5A Schottky diode | SS54 | |
| R1 | 200k,1%,0603 | | |
| R2 | 10.5k,1%,0603 | | |
| R3 | 1MΩ, 0603 | | |

## Recommend Components for Typical Applications

| $V_{OUT}$(V) | R1(kΩ) | R2(kΩ) | L(μH) | C3 |
|---|---|---|---|---|
| 12 | 200 | 10.5 | 2.2 | 2×22μF/25V/X7R,1206 |

## Layout Design

To achieve optimal design, follow these PCB layout considerations:

- Place $C_{IN}$, L, R1, and R2 close to the IC
- To achieve the best thermal and noise performance, maximize the PCB copper area connecting to the GND pin. A ground plane is highly recommended if cost allows.
- $C_{IN}$ must be close to pins IN and GND. Minimize the loop area formed by $C_{OUT}$, LX, and GND.
- To reduce the switching noise, minimize the PCB copper area connected to the LX pin.
- In order to reduce crosstalk, R1, R2, and the trace connected to the FB pin must not be adjacent to the LX net on the PCB layout.
- If the system controller interfacing with the EN pin has a high impedance state during shutdown mode, and the IN pin is connected directly to a power source such as a Li-ion battery, add a 1MΩ pulldown resistor between the EN and GND pins to prevent noise from falsely triggering the regulator during shutdown mode.

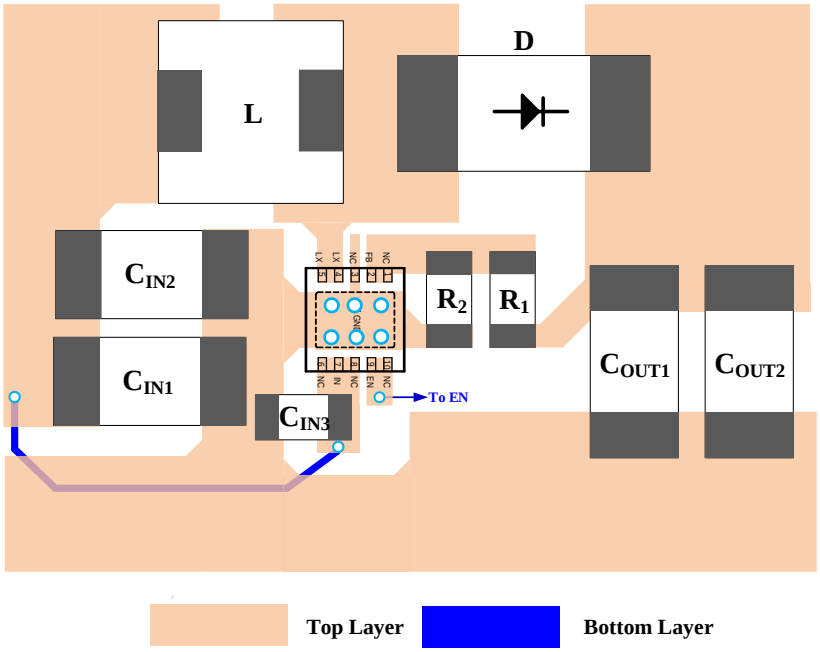
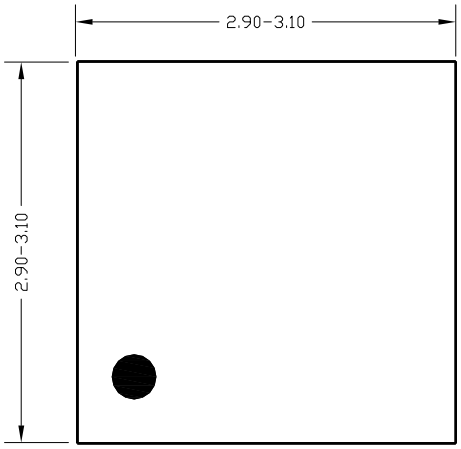
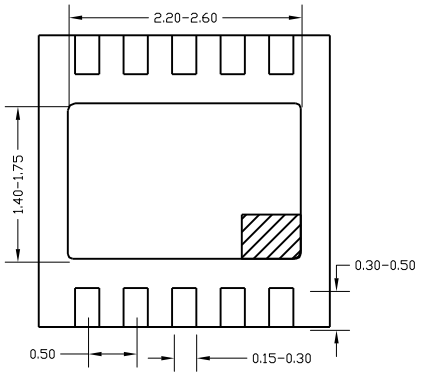



*Figure 4. Suggested PCB Layout*

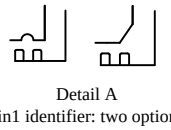
# DFN3x3-10 Package Outline and PCB Layout



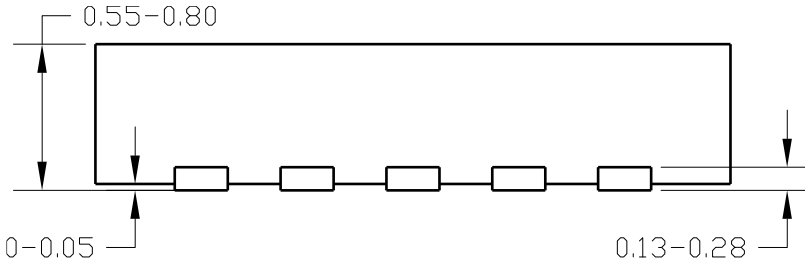

Top view



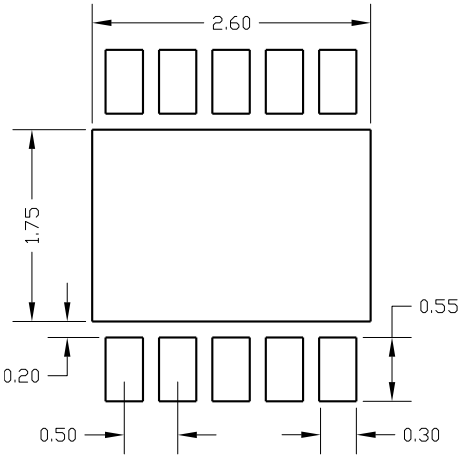

Bottom view



Detail A
Pin1 identifier: two option




Side view

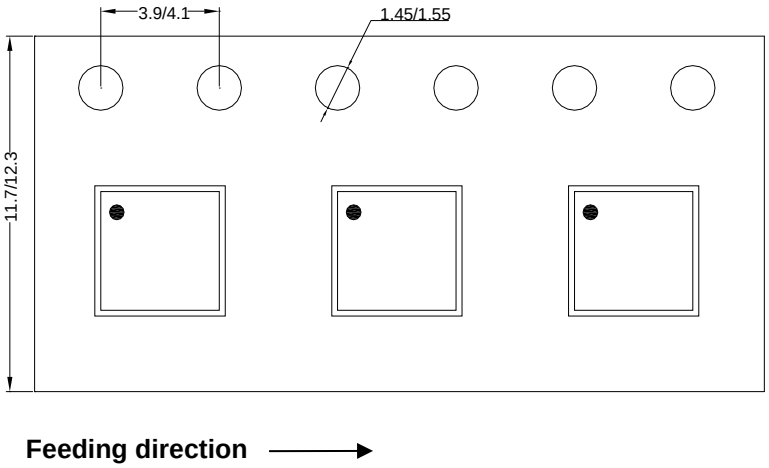



Recommended pad layout
(reference only)

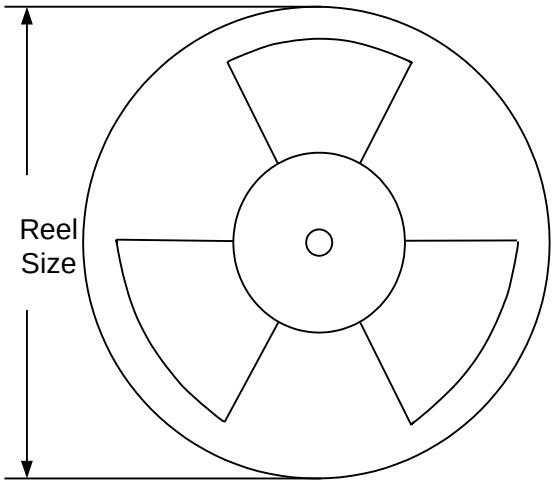
***Note:*** *All dimensions are in millimeters and exclude mold flash and metal burr.*

# Taping and Reel Specification

## DFN3×3-10 taping orientation




## Carrier tape and reel specification for packages




| Package types | Tape width (mm) | Pocket pitch(mm) | Reel size (Inch) | Trailer length(mm) | Leader length (mm) | Qty per reel |
|---|---|---|---|---|---|---|
| **DFN3×3** | **10** | **8** | **13"** | **400** | **400** | **5000** |

Others: NA

# Revision History

The revision history provided is for informational purposes only and is believed to be accurate, however, not warranted. Please make sure that you have the latest revision.

| Date | Revision | Change |
|---|---|---|
| Apr.20, 2023 | Revision 1.0 | Language improvements for clarity. |
| Sep.27, 2013 | Revision 0.9 | Initial Release |

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